

## **Laser writer process policy**

1. Minimum feature sizes between 4  $\mu\text{m}$  and 50  $\mu\text{m}$  will be allowed.
2. The design (.cif) should be checked and approved by the system owner/operator. After approval, the design should be burned in a disk and submitted to the operator at least 24 hours before the slot.
3. The writing area of the design should be 2"X 2" for a 3 inch mask plate and 4" X 4" for a 5" mask plate. The design should be within the wafer outline boundary. The user should be ready to modify their design according to our parameters.
4. The mask plate issue request should be submitted. This is available in the online module in CEN website. The request should be approved by the guide. Without online approval, mask cannot be written.
5. The etching of the mask plate will be conducted once in a week. User should send a mail with Guide approval if they want the mask plate urgently.